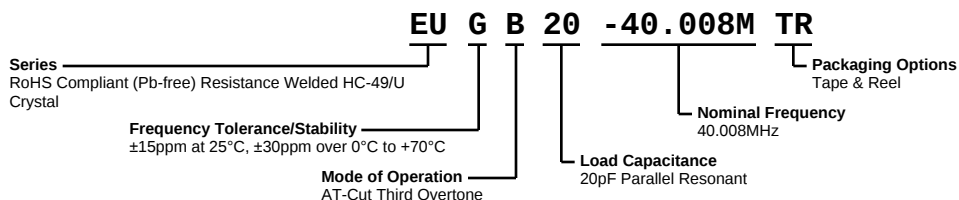


EUGB20-40.008M TR



ELECTRICAL SPECIFICATIONS

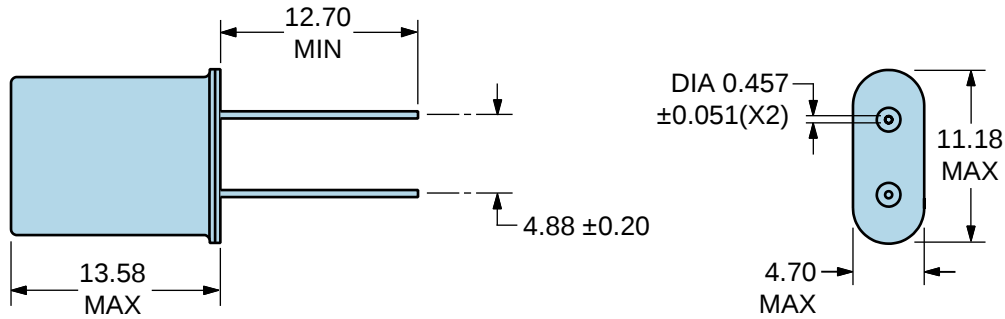
Nominal Frequency	40.008MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C , $\pm 30\text{ppm}$ over 0°C to $+70^\circ\text{C}$
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Load Capacitance	20pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Third Overtone
Drive Level	2mWatts Maximum
Storage Temperature Range	-40°C to $+125^\circ\text{C}$
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Lead Termination	Sn $2\mu\text{m}$ - $6\mu\text{m}$
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

EUGB20-40.008M TR

MECHANICAL DIMENSIONS (all dimensions in millimeters)

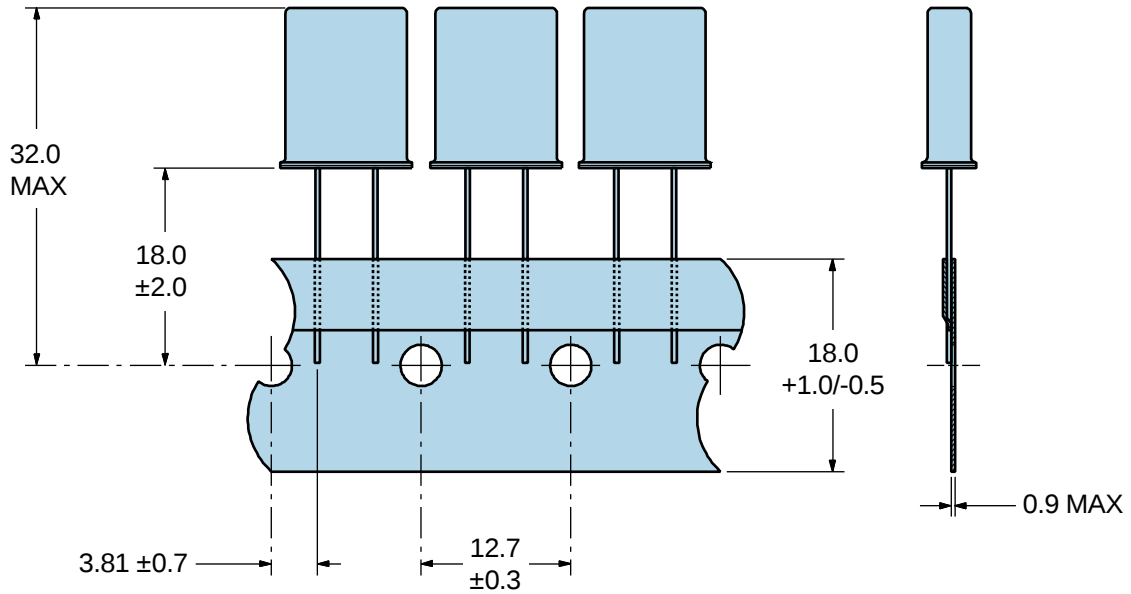


LINE	MARKING
1	ECLIPTEK
2	E40.008M <i>E=Configuration Designator</i>
3	XX <i>XX=Ecliptek Manufacturing Code</i>

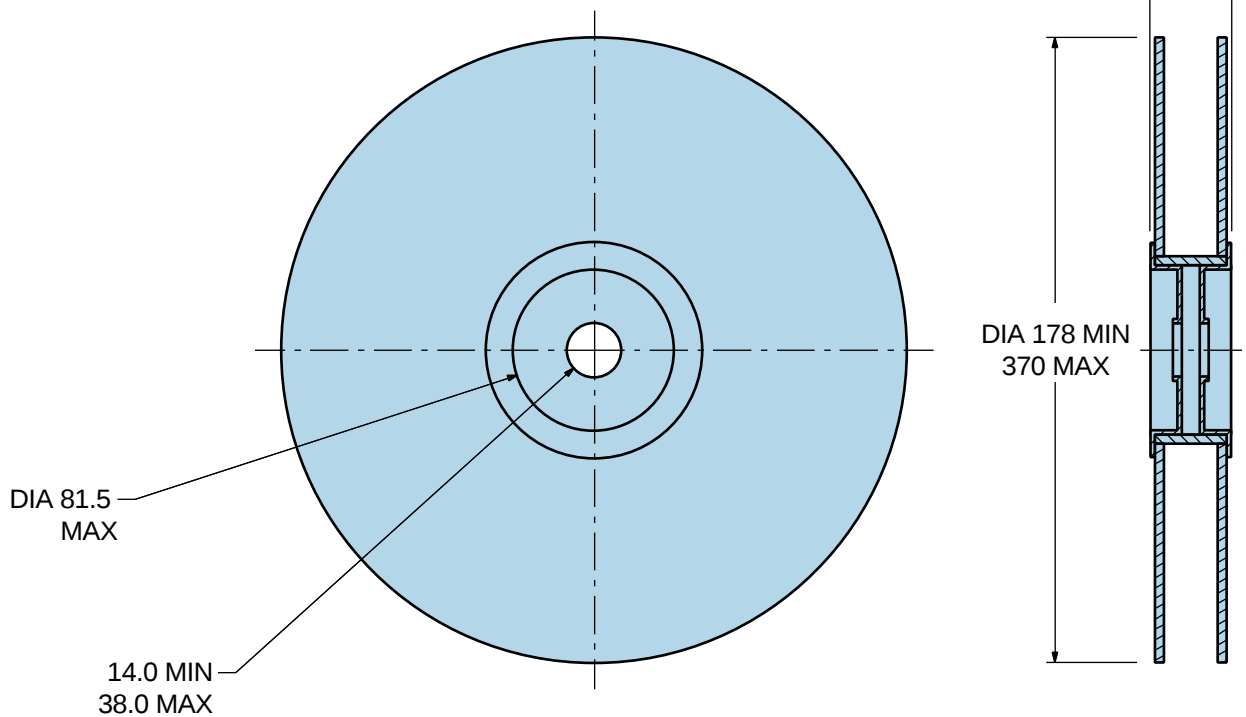
EUGB20-40.008M TR

Tape & Reel Dimensions

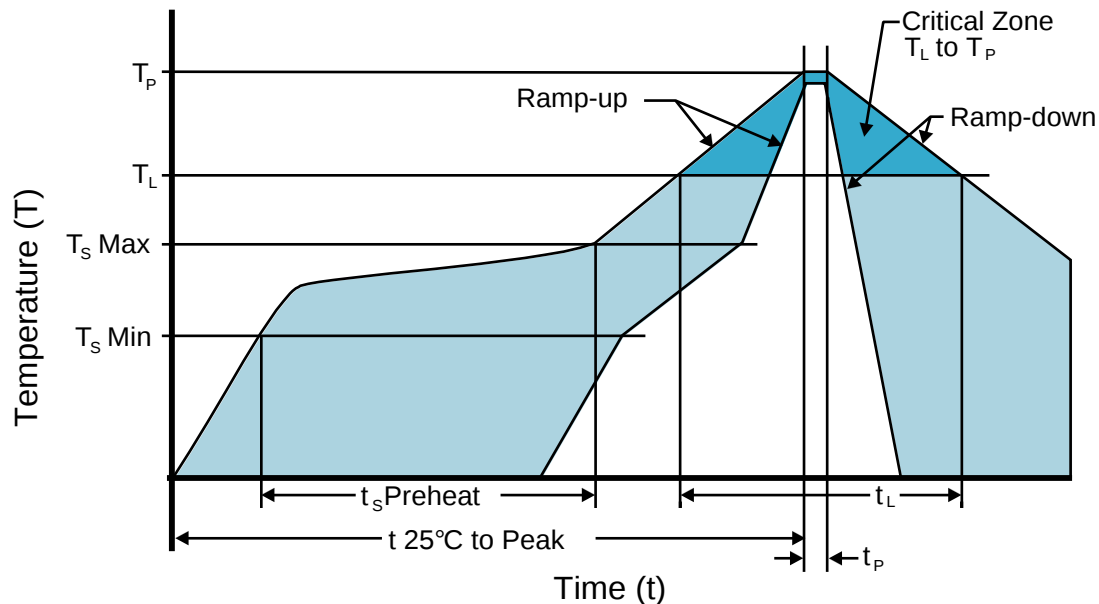
Quantity Per Reel: 1,000 units



*Compliant to EIA 468B



Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)	3°C/second Maximum
------------------------------------	--------------------

Preheat

- Temperature Minimum (TS MIN)	150°C
- Temperature Typical (TS TYP)	175°C
- Temperature Maximum (TS MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (TL to TP)	3°C/second Maximum
--------------------------------	--------------------

Time Maintained Above:

- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
------------------------------	--------------------------------------

Target Peak Temperature (TP Target)	250°C +0/-5°C
--	---------------

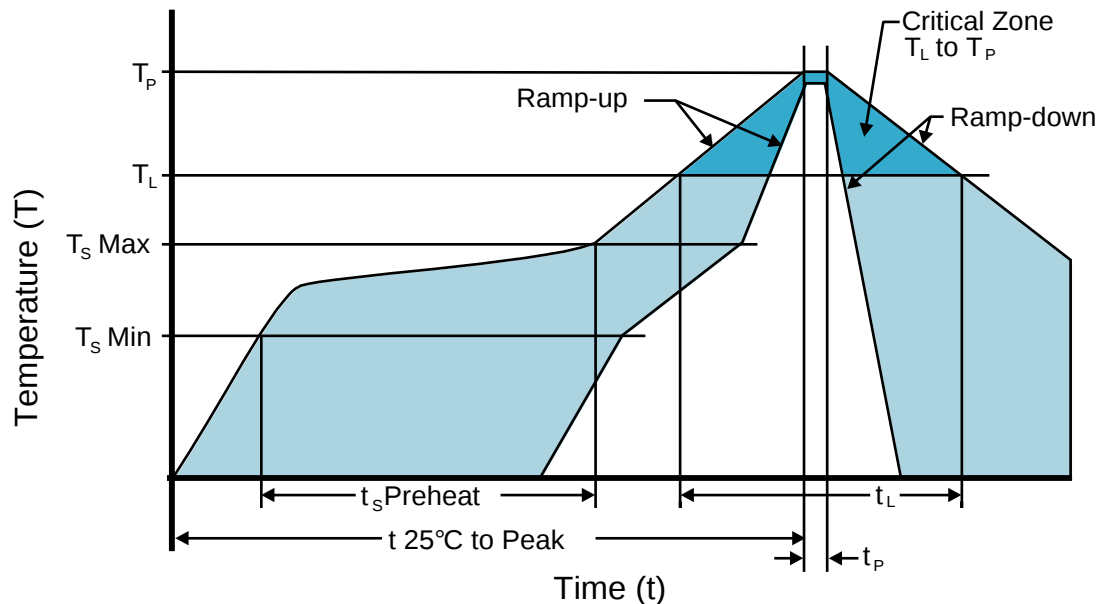
Time within 5°C of actual peak (tp)	20 - 40 seconds
--	-----------------

Ramp-down Rate	6°C/second Maximum
-----------------------	--------------------

Time 25°C to Peak Temperature (t)	8 minutes Maximum
--	-------------------

Moisture Sensitivity Level	Level 1
-----------------------------------	---------

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
 - Temperature Typical (T_S TYP) 150°C
 - Temperature Maximum (T_S MAX) N/A
 - Time (t_s MIN) 30 - 60 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
 - Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 245°C Maximum

Target Peak Temperature (T_P Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak (t_p) 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.